

Mitsui HSD Application Foil Roadmap



高速訊號傳輸用電解銅箔

Copper foil for the HSD(High Speed Digital) application



針對更加高頻高速的需求,發展更低耗損的銅箔材料

Developing copper foil that achieve sufficiently low loss to meet increasing demand for higher-speed transmission.



多樣化的樹脂匹配性,運用獨有的技術來達到低耗損及良好結合力的目標

Achieved both low loss and sufficient adhesion reliability for diversified resin systems by applying our unique technology.

